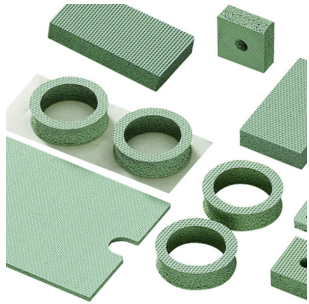


Data sheet Product WSF 48



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- elastomer foam with closed cell structure
- good heat conductor e.g. between components, heatsinks and casing parts
- electrical insulating
- can be compressed even with a low contact pressure
- absorbs shocks and vibrations

Thermal resistance at 3.2 mm material thickness:

| | | | | |
|---|---------|-----|------|------|
| compression [%] | contact | 10 | 25 | 50 |
| contact pressure [psi] | >1 | 5 | 12 | 34 |
| R_{th} [K/W] (1 in ² x 3.2 mm) | 6 | 4.5 | 2.5 | 1 |
| heat conductivity [W/mK] | 0.3 | 0.4 | 0.45 | 0.65 |

- **WSFS 635** double sided adhesive and **WSF** self-adhesive upon request
- according to NASA gas emission requirements

Features

material:

foam film

Material:

100mm 11111

| | |
|--------------------------|--|
| material thickness: | 4.8^{±0,800} mm |
| version: | non adhesive |
| colour: | green |
| density: | 1.105 g/cm³ |
| hardness: | 13 Shore A |
| temperature range: | -62°C ... +205°C |
| thermal conductivity: | 0.108 W/m·K (substrate) |
| compression, 25%: | 18 psi |
| elongation: | 150 % |
| tear strength: | 120 psi |
| dielectric strength: | 4 kV/mm |
| class of inflammability: | UL 94 V-1 (at thickness ≥3.2mm) |
| type of delivery: | <ul style="list-style-type: none"> • plates, usable area 914x914mm • other dimensions upon request |